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 NEWS 2 "Ask CAS" for self-help around the clock  
 NEWS 3 SEP 09 CA/CAPLUS records now contain indexing from 1907 to the present  
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 NEWS 8 AUG 18 FROSTI and KOSMET enhanced with Simultaneous Left and Right Truncation  
 NEWS 9 AUG 18 Simultaneous left and right truncation added to ANABSTR  
 NEWS 10 SEP 22 DIPPR file reloaded  
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 NEWS 12 SEP 29 DISSABS now available on STN  
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 NEWS 14 OCT 21 BIOSIS file reloaded and enhanced  
 NEWS 15 OCT 28 BIOSIS file segment of TOXCENTER reloaded and enhanced

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```
=> s phenol novolak resin#
L1      1107 PHENOL NOVOLAK RESIN#

=> s crude and l1
L2      83 CRUDE AND L1

=> s l2 and ortho
L3      11 L2 AND ORTHO

=> s l3 and catalyst# and (sulfuric or benzenesulfonic or toluenesulfonic)
L4      4 L3 AND CATALYST# AND (SULFURIC OR BENZENESULFONIC OR TOLUENESULFONIC)

=> d 14 1-4
```

L4 ANSWER 1 OF 4 EUROPATFULL COPYRIGHT 2003 WILA on STN

Full  
Text

PATENT APPLICATION - PATENTANMELDUNG - DEMANDE DE BREVET

```
AN      1275673 EUROPATFULL ED 20030127 EW 200303 FS OS
TIEN    Epoxy resin composition, cured article thereof, novel epoxy resin, novel
        phenol compound, and process for preparing the same.
TIDE    Epoxidharzzusammensetzung, daraus hergestellter gehaertete Gegenstand,
        neues Epoxidharz, neue Phenolverbindung, und Verfahren zu deren
        Herstellung.
TIFR    Composition de resine epoxy, article reticule, nouvelle resine epoxy,
        nouveau compose phenolique et procede de preparation.
IN      Ogura, Ichiro, 614-56, Iriyamazu, Ichihara-shi, Chiba-ken, JP;
        Takahashi, Yoshiyuki, 3-46-28, Chiharadai, Ichihara-shi, Chiba-ken, JP;
        Imada, Tomoyuki, 3-27-6-107, Tatsumidai-higashi, Ichihara-shi,
        Chiba-ken, JP
PA      DAINIPPON INK AND CHEMICALS, INC., 35-58, Sakashita 3-chome, Itabashi-ku
        Tokyo, JP
SO      Wila-EPZ-2003-H03-T1a
DS      R AT; R BE; R BG; R CH; R CY; R CZ; R DE; R DK; R EE; R ES; R FI; R FR;
        R GB; R GR; R IE; R IT; R LI; R LU; R MC; R NL; R PT; R SE; R SK; R TR;
        R AL; R LT; R LV; R MK; R RO; R SI
PIT     EPA2 EUROPAEISCHE PATENTANMELDUNG
PI      EP 1275673          A2 20030115
OD      20030115
AI      EP 2002-14977      20020709
PRAI    JP 2001-2001212069 20010712
        JP 2001-2001326305 20011024
IC      ICM C08G059-00
```

L4 ANSWER 2 OF 4 USPATFULL on STN

Full  
Text

References

```
AN      2003:134763 USPATFULL
TI      Epoxy resin composition, cured article thereof, novel epoxy resin, novel
        phenol compound, and process for preparing the same
IN      Ogura, Ichiro, Ichihara-shi, JAPAN
        Takahashi, Yoshiyuki, Ichihara-shi, JAPAN
        Imada, Tomoyuki, Ichihara-shi, JAPAN
PA      Dainippon Ink and Chemicals, Inc., Tokyo, JAPAN (non-U.S. corporation)
PI      US 2003092852      A1 20030515
AI      US 2002-190491      A1 20020709 (10)
PRAI    JP 2001-212069      20010712
        JP 2001-326305      20011024
DT      Utility
FS      APPLICATION
```

LN.CNT 904  
 INCL INCLM: 525/403.000  
 INCLS: 549/200.000  
 NCL NCLM: 525/403.000  
 NCLS: 549/200.000  
 IC [7]  
 ICM: C07D321-00  
 ICS: C08G065-32  
 CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L4 ANSWER 3 OF 4 USPATFULL on STN

Full Text	CITE References
AN 2002:172464	USPATFULL
TI Method of producing novolak resin	
IN Saito, Noriaki, Toyonaka-shi, JAPAN	
Aizu, Ichishi, Niihama-shi, JAPAN	
Nakajima, Nobuyuki, Niihama-shi, JAPAN	
Fujiwara, Masahiro, Niihama-shi, JAPAN	
Yano, Koji, Niihama-shi, JAPAN	
PA SUMITOMO CHEMICAL COMPANY, LIMITED (non-U.S. corporation)	
PI US 2002091224	AI 20020711
AI US 2001-364	AI 20011204 (10)
<u>PRAI JP 2000-377258</u>	20001212
<u>JP 2000-377259</u>	20001212
<u>JP 2001-153632</u>	20010523
DT Utility	
FS APPLICATION	
LN.CNT 579	
INCL INCLM: 528/129.000	
NCL NCLM: 528/129.000	
IC [7]	
ICM: C08G008-04	
CAS INDEXING IS AVAILABLE FOR THIS PATENT.	

L4 ANSWER 4 OF 4 USPATFULL on STN

Full Text	CITE References
AN 1998:4379	USPATFULL
TI Positive resin composition sensitive to ultraviolet rays	
IN Kawabe, Yasumasa, Haibara-gun, Japan	
Yamanaka, Tsukasa, Haibara-gun, Japan	
Aoi, Toshiaki, Haibara-gun, Japan	
PA Fuji Photo Film Co., LTD., Kanagawa, Japan (non-U.S. corporation)	
PI US 5707776	19980113
<u>AI US 1995-438481</u>	19950510 (8)
<u>PRAI JP 1994-98671</u>	19940512
DT Utility	
FS Granted	
LN.CNT 1881	
INCL INCLM: 430/270.100	
INCLS: 430/920.000; 430/921.000; 430/905.000; 430/171.000; 430/176.000;	
522/166.000	
NCL NCLM: 430/270.100	
NCLS: 430/171.000; 430/176.000; 430/905.000; 430/920.000; 430/921.000;	
522/166.000	
IC [6]	
ICM: G03C001-73	
EXF 430/270; 430/920; 430/921; 430/905; 430/171; 430/176; 522/166	
CAS INDEXING IS AVAILABLE FOR THIS PATENT.	

=> s phenol# and (aldehyde or formaldehyde) and pressure

L5 59271 PHENOL# AND (ALDEHYDE OR FORMALDEHYDE) AND PRESSURE

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=> s 15 and heat# and condenser
L6      5830 L5 AND HEAT# AND CONDENSER

=> s 16 and reflux?
L7      4419 L6 AND REFLUX?

=> s 17 and ortho
L8      1151 L7 AND ORTHO

=> s 18 and phenol novolak resin#
L9      6 L8 AND PHENOL NOVOLAK RESIN#

=> d 19 1-6
```

L9 ANSWER 1 OF 6 EUROPATFULL COPYRIGHT 2003 WILA on STN

Full  
Text

PATENT APPLICATION - PATENTANMELDUNG - DEMANDE DE BREVET

```
AN      435502 EUROPATFULL ED 20000813 EW 199127 FS OS STA B
TIEN    Method of preparing high glass transition temperature novolak resins
        useful in high resolution photoresist compositions.
TIDE    Verfahren zur Herstellung von Novolakharzen mit hoher
        Glasuebergangstemperatur, verwendbar bei lichtempfindlichen
        Fotowiderstand-Harzzusammensetzungen mit hoher Aufloesung.
TIFR    Procede de preparation d'une resine novolaque a haute temperature de
        transition vitreuse utilisable pour des compositions d'agents
        photoresistants a haute resolution.
IN      Bogan, Leonard Edward, Jr., 325 Moyer Road, Harleysville, Pennsylvania
        19438, US
PA      ROHM AND HAAS COMPANY, Independence Mall West, Philadelphia Pennsylvania
        19105, US
SO      Wila-EPZ-1991-H27-T1
DS      R AT; R BE; R CH; R DE; R DK; R ES; R FR; R GB; R GR; R IT; R LI; R LU;
        R NL; R SE
PIT     EPAL EUROPAEISCHE PATENTANMELDUNG
PI      EP 435502          A1 19910703
OD      19910703
AI      EP 1990-313404      19901210
PRAI    US 1989-452027      19891218
IC      ICM C08G008-24
        ICS G03F007-023      C08G008-08
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L9 ANSWER 2 OF 6 EUROPATFULL COPYRIGHT 2003 WILA on STN

Full  
Text

GRANTED PATENT - ERTEILTES PATENT - BREVET DELIVRE

```
AN      219928 EUROPATFULL ED 20020307 EW 199218 FS PS STA B
TIEN    Epoxy fluorocarbon coating composition and process to make same.
TIDE    Ueberzugsmittelzusammensetzung aus Epoxidharzen und Fluorcarbonpolymeren
        und Verfahren zu deren Herstellung.
TIFR    Composition de revetement a base d'une resine epoxyde et d'un polymere
        fluorocarbone et procede de preparation de cette composition.
IN      Giordano, Paul J., 5595 Hummelfine Drive, Hudson Ohio, US;
        Smierciak, Richard C., 9285 June Drive, Streetsboro Ohio, US
PA      THE STANDARD OIL COMPANY, 200 Public Square, 36-F-3454, Cleveland Ohio
        44114, US
SO      Wila-EPS-1992-H18-T1
DS      R DE; R FR; R GB
PIT     EPB1 EUROPAEISCHE PATENTENSCHRIFT
```

PI	EP 219928	B1	19920429
OD			19870429
AI	EP 1986-305599		19860722
PRAI	US 1985-777890		19850919
	US 1986-856625		19860425
REP	DE 1519010 A	DE	2122408 A
	DE 2264132 A	FR	2396785 A
	US 2777783 A	US	3023189 A
IC	ICM C09D163-00		
	ICS C08L063-00		

L9 ANSWER 3 OF 6 USPATFULL on STN

Full Text	Citing References
AN	2002:172464 USPATFULL
TI	Method of producing novolak resin
IN	Saito, Noriaki, Toyonaka-shi, JAPAN
	Aizu, Ichishi, Niihama-shi, JAPAN
	Nakajima, Nobuyuki, Niihama-shi, JAPAN
	Fujiwara, Masahiro, Niihama-shi, JAPAN
	Yano, Koji, Niihama-shi, JAPAN
PA	SUMITOMO CHEMICAL COMPANY, LIMITED (non-U.S. corporation)
PI	US 2002091224 A1 20020711
AI	US 2001-364 A1 20011204 (10)
PRAI	JP 2000-377258 20001212
	JP 2000-377259 20001212
	JP 2001-153632 20010523
DT	Utility
FS	APPLICATION
LN.CNT	579
INCL	INCLM: 528/129.000
NCL	NCLM: 528/129.000
IC	[7]
	ICM: C08G008-04

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L9 ANSWER 4 OF 6 USPATFULL on STN

Full Text	Citing References
AN	93:44346 USPATFULL
TI	Phenolic resin and method for preparing same
IN	Ando, Shinji, Nagoya, Japan
	Fukui, Yukio, Nagoya, Japan
	Iimuro, Shigeru, Nagoya, Japan
PA	Mitsui Toatsu Chemicals, Inc., Tokyo, Japan (non-U.S. corporation)
PI	US 5216112 19930601
AI	US 1991-745422 19910815 (7)
PRAI	JP 1990-216984 19900820
	JP 1990-216985 19900820
	JP 1990-262984 19901002
	JP 1991-39940 19910306
DT	Utility
FS	Granted
LN.CNT	951
INCL	INCLM: 528/157.000
	INCLS: 528/129.000; 528/144.000; 528/165.000
NCL	NCLM: 528/157.000
	NCLS: 528/129.000; 528/144.000; 528/165.000
IC	[5]
	ICM: C08G008-04
	ICS: C08G014-04
EXF	528/129; 528/165; 528/144; 528/157

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L9 ANSWER 5 OF 6 USPATFULL on STN

	Full Text	Citing References
AN	91:30357	USPATFULL
TI	Epoxy fluorocarbon coating compositions and the process to make the same	
IN	Giordano, Paul J., Hudson, OH, United States	
	Smierciak, Richard C., Streetsboro, OH, United States	
PA	The Standard Oil Company, Cleveland, OH, United States (U.S. corporation)	
PI	US 5008135	19910416
AI	US 1990-554933	19900718 (7)
RLI	Continuation of Ser. No. <u>US 1989-334736</u> , filed on 7 Apr 1989, now abandoned which is a continuation of Ser. No. <u>US 1988-186673</u> , filed on 21 Apr 1988, now abandoned which is a continuation of Ser. No. <u>US 1986-856625</u> , filed on 25 Apr 1986, now abandoned which is a continuation-in-part of Ser. No. <u>US 1985-777890</u> , filed on 19 Sep 1985, now abandoned	
DT	Utility	
FS	Granted	
LN.CNT	781	
INCL	INCLM: 427/386.000	
	INCLS: 523/169.000; 523/435.000; 525/113.000; 525/121.000	
NCL	NCLM: 427/386.000	
	NCLS: 523/169.000; 523/435.000; 525/113.000; 525/121.000	
IC	[5]	
	ICM: C08L063-00	
	ICS: C08L027-18	
EXF	523/169; 523/435; 525/113; 525/121; 427/386	
CAS INDEXING IS AVAILABLE FOR THIS PATENT.		

L9 ANSWER 6 OF 6 USPATFULL on STN

	Full Text	Citing References
AN	87:78024	USPATFULL
TI	Thermosettable <b>heat</b> -resistant resin compositions	
IN	Saito, Yasuhisa, Osaka, Japan	
	Takagishi, Hisao, Kyoto, Japan	
	Watanabe, Katsuya, Osaka, Japan	
	Okuno, Kohichi, Osaka, Japan	
	Kenmei, Junichi, Hyogo, Japan	
	Kamio, Kunimasa, Osaka, Japan	
PA	Sumitomo Chemical Company, Limited, Osaka, Japan (non-U.S. corporation)	
PI	US 4705833	19871110
AI	<u>US 1985-813272</u>	19851224 (6)
PRAI	<u>JP 1985-7017</u>	19850117
	<u>JP 1985-58966</u>	19850323
DT	Utility	
FS	Granted	
LN.CNT	596	
INCL	INCLM: 525/504.000	
	INCLS: 525/423.000; 528/099.000; 528/108.000; 528/109.000; 528/113.000; 528/117.000; 528/322.000	
NCL	NCLM: 525/504.000	
	NCLS: 525/423.000; 528/099.000; 528/108.000; 528/109.000; 528/113.000; 528/117.000; 528/322.000	
IC	[4]	
	ICM: C08G059-44	
	ICS: C08G059-54	
EXF	528/113; 528/117; 528/322; 528/363; 528/99; 528/108; 528/109; 525/423; 525/504	
CAS INDEXING IS AVAILABLE FOR THIS PATENT.		

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